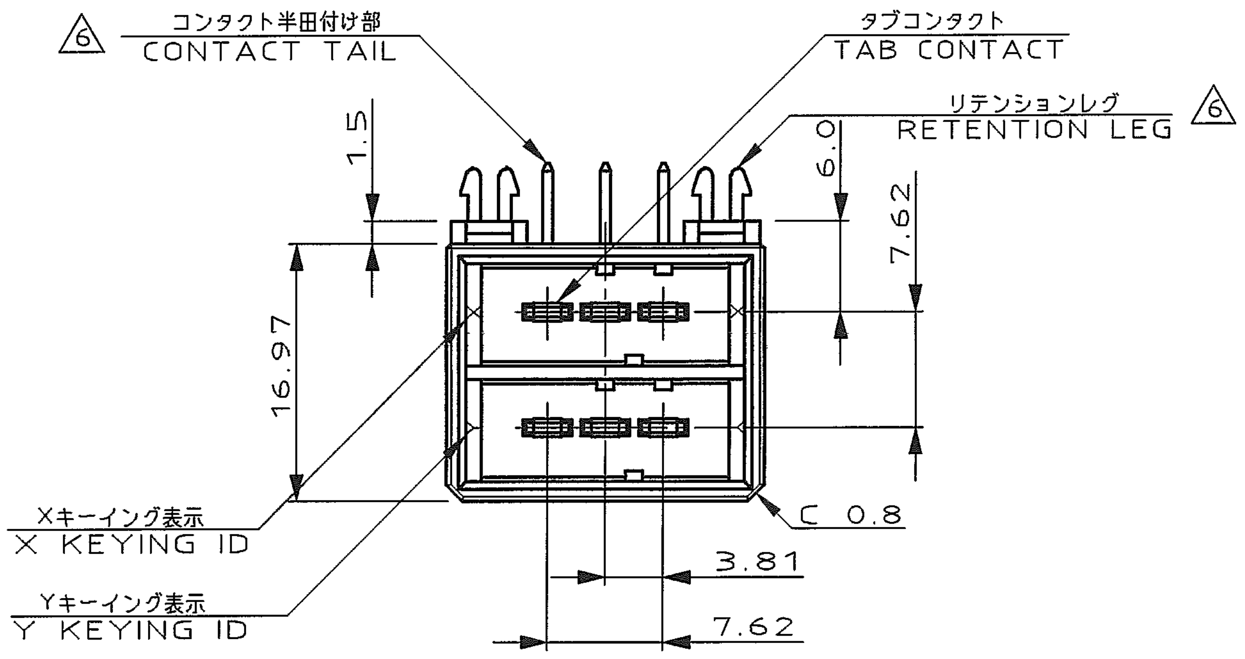
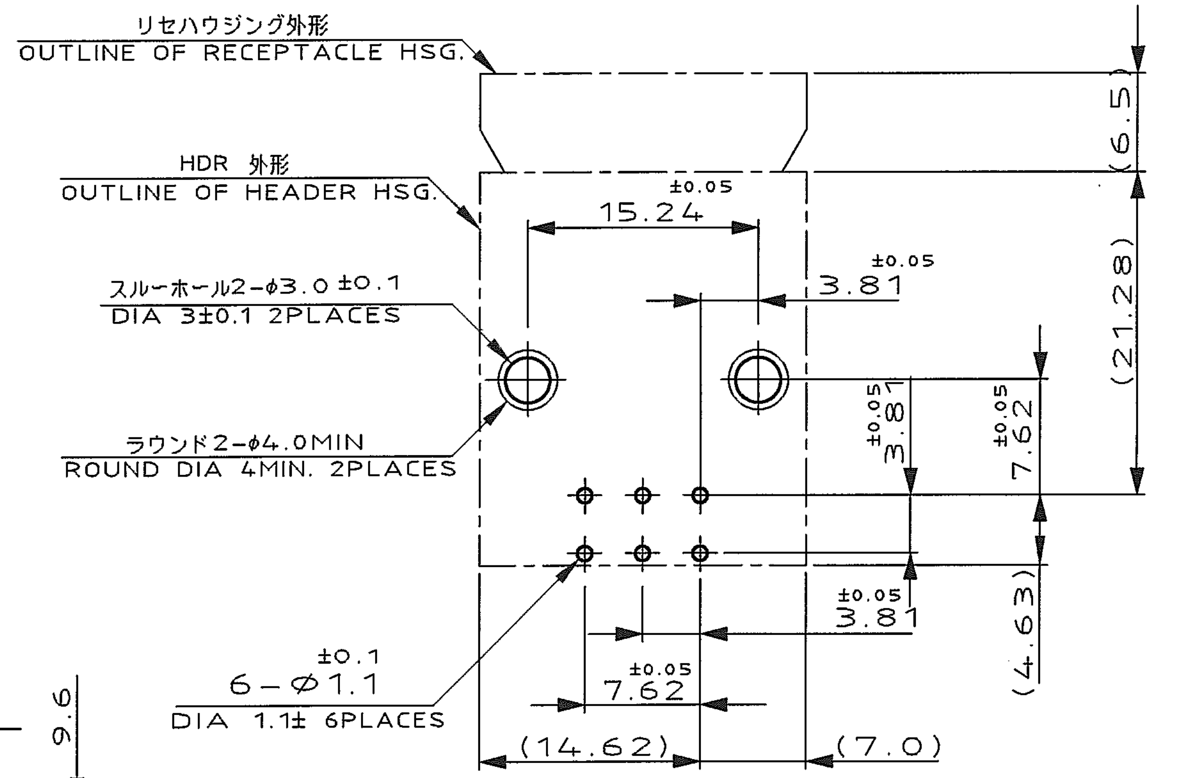
4 3 2 1

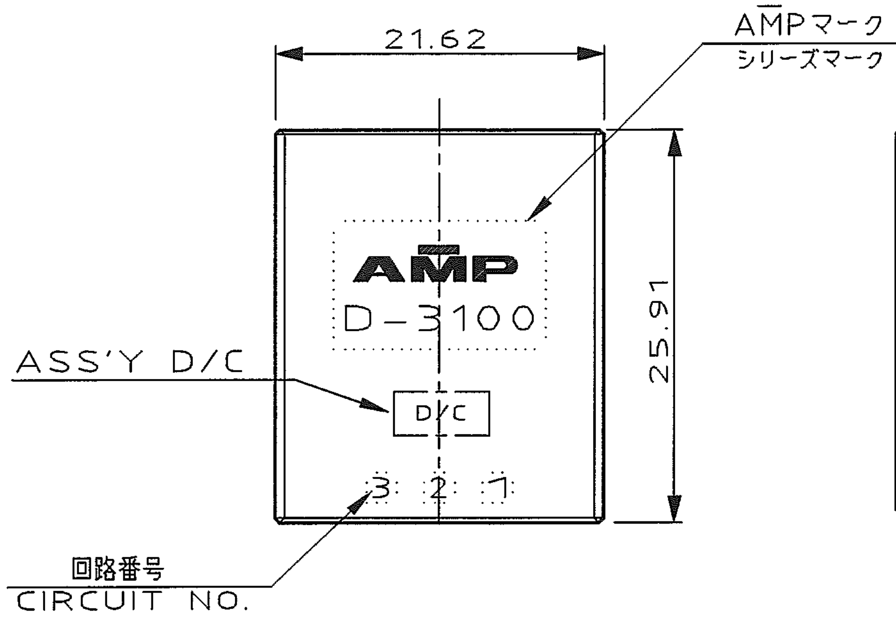
NUMBER 178137

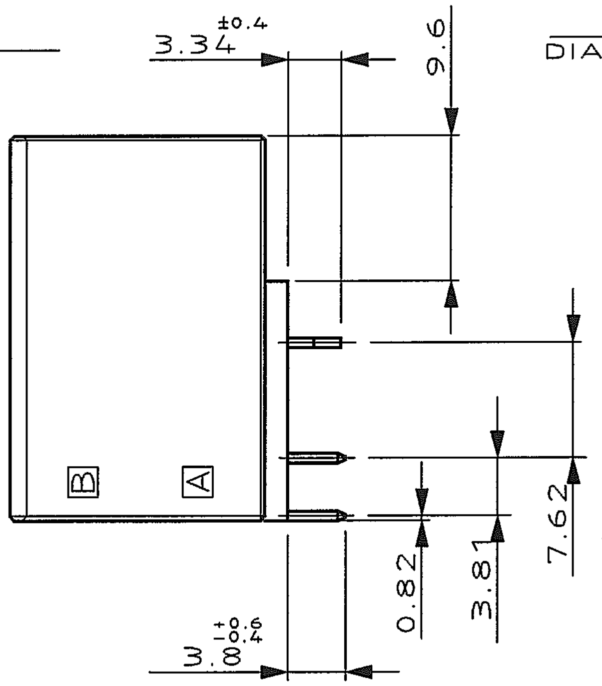
3rd ANGLE PROJECTION

METRIC









（非累積公差）

推奨基板取付け穴寸法　（コネクタ搭載面）

RECOMEND PC BOARD HOLL PATTERN(NOT ACCUMLATE TOLERANCE)

PC BOARD THICKNEES;1.6±0.1 (PC 基板厚;1.6±0.1)

注記

△1 材料；ハウジング；ガラス入りポリエステル樹脂
コンタクト；銅合金　熱可塑性ポリエステル樹脂
リテンションレグ；銅合金

△2 めっき：(コンタクト接触部)ニッケル下地の上に 0.38μMIN金メッキ

△3 めっき：(コンタクト接触部)ニッケル下地の上に 0.76μMIN金メッキ

△4 めっき：(コンタクト全面)ニッケル下地の上に 2.0 μMINスズメッキ

~~△5 (リテンションレグとコンタクト半田付け部)ニッケル下地の上に半田メッキ~~

△6 .めっき：リテンションレグとコンタクト半田付部
：ニッケル下地の上にスズめっき

NOTES

△1 MATERIAL HOUSING:GLASS FILED POLYESTER
CONTACT:COPPER ALLOY
RETENTION LEG:COPPER ALLOY

△2 FINISH(CONTACT AREA):0.38μMIN GOLD PLATED OVER NICKEL

△3 FINISH(CONTACT AREA):0.76μMIN GOLD PLATED OVER NICKEL

△4 FINISH(CONTACT):2.0 μMIN TIN PLATED OVER NICKEL

~~△5 FINISH(RETENTION LEG AND CONTACT TAIL):TIN-LEAD PLATED OVER NICKEL~~

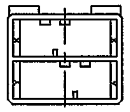
△6 .FINISH(RETENTION LEG): TIN PLATED
(CONTACT TAIL) OVER NICKEL

C

B

A

DIMENSIONS IN MILLIMETERS. DO NOT SCALE PRINT

KEYING LOCATION	KEYING NAME	FINISH	PART NO.
	XY	△6 △4	3-178137-5
		△6 △3	3-178137-3
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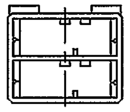	YY	△6 △4	2-178137-5
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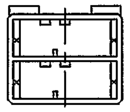	XX	△6 △4	1-178137-5
		△6 △3	1-178137-3
		△6 △2	1-178137-2

PRINT DIST

LTR	REVISION RECORD	DR	CHK	DATE
C1	REVISED PER ECO-11-005030	RK	HMR	24MAR11

TE Connectivity

WIRE RANGE ~~mm² (AWG -)~~	~~INSULATION DIA~~ - mmφ	NAME DYNAMIC D-3100 3.81 X 7.62 PITCH(H) 6POS. HDR CONN. ASS'Y (KEY;XX,YY,XY)
MATERIAL SEE NOTE 注記参照	FINISH SEE NOTE 注記参照	一般公差 (GENERAL TOLERANCE) 10以下 ±0.3 10を超え 30以下 ±0.4 30を超え100以下 ±0.45 角度 ±3°
DR. 1-JULY-`92 Y.TANAKA	DE. 1-JULY-`92 Y.TANAKA	SIZE A3 / LOC J / NUMBER C-178137
CHK. 6-JUL-`92 S.MANABE	APP. 6-JUL-`92 S.MANABE	SCALE 2-1 / REV. C1 / SHEET 1 OF 1

(CUSTOMER DRAWING) 顧客用図面